

Process Change Notice #1106071

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PCN Date: 07June2011		Effective Date: 07June2011					
Title: Si53x Datasheet Revision from 1.1 to 1.2							
Originator: Jason Rock	Phone: 512-532-5	997	Dept: WL Timing Marketing				
Customer Contact: Kathy Haggar	Phone: 512-532-5261		Dept: Sales				
PCN Type:							
☐ Assembly ☐ Discont	atinuance						
□ Datasheet □ Fabrication □ Product Revision							
☐ Packing ☐ Labelin	g 🗆 L	ocatior	n 🗌 Other				
Last Order Date: N/A							
PCN Details							
Description of Change:							
Silicon Labs is pleased to announce rev 1.2 for the Si530, Si531, Si532, Si533, Si534 devices. Please refer to Appendix A for a list of document changes and access to these datasheets online.							
Reason for Change: To ensure datasheets are consistent with the functionality of the Si53x devices							
Impact on Form, Fit, Function, Quality, Reliability: There is no impact on form, fit, function, quality or reliability							
Product Identification: Si530, Si531, Si532, Si533, Si534							
Last Date of Unchanged Product: N/A							
Qualification Samples: N/A							
Customer Early Acceptance Sign Off:							
Customers may approve early PCN acceptance by completing the information below:							
Early Acceptance Date:							
Name:							
Company:							
Email your early Acceptance approval to: <u>katherine.haggar@silabs.com</u>							
Qualification Data: N/A							



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Appendix A:

□ Updated 2.5 V/3.3 V and 1.8 V CML output level specifications for Table 3 on page 3.

Si530/31	datasheet	revision '	1.1 to	v1.2	changes:
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□ Added footnotes clarifying max offset frequency test conditions for Table 4 on page 4.
 □ Added CMOS phase jitter specs to Table 4 on page 4. □ Removed the words "Differential Modes: LVPECL/LVDS/CML" in footnote referring to AN256 in Table 4 on page 4.
□ Separated 1.8 V, 2.5 V/3.3 V supply voltage specifications in Table 8 on page 5.
☐ Updated and clarified Table 8 on page 5 to include the "Moisture Sensitivity Level" and "Contact Pads" rows.
□ Updated Figure 3 on page 9 and Table 12 on page 9 to reflect specific marking information. Previously, Figure 3
was generic.
Si532 datasheet revision 1.1 to v1.2 changes:
□ Updated 2.5 V/3.3 V and 1.8 V CML output level specifications for Table 3 on page 3.
□ Added footnotes clarifying max offset frequency test conditions for Table 4 on page 4.
□ Removed the words "Differential Modes: LVPECL/LVDS/CML" in footnote referring to AN256 in Table 4 on page 4. □ Added CMOS phase jitter specs to Table 4 on page 4.
□ Updated Table 8 on page 5 to include the "Moisture Sensitivity Level" and "Contact Pads" rows.
□ Updated Figure 3 and Table 11 on page 9 to reflect specific marking information. Previously, Figure 3 was generic.
Si533 datasheet revision 1.1 to v1.2 changes:
□ Updated 2.5 V/3.3 V and 1.8 V CML output level specifications for Table 3 on page 3.
□ Added footnotes clarifying max offset frequency test conditions for Table 4 on page 4.
□ Removed the words "Differential Modes: LVPECL/LVDS/CML" in footnote referring to AN256 in Table 4 on page 4. □ Added CMOS phase jitter specs to Table 4 on page 4.
☐ Updated Table 8 on page 5 to include the "Moisture Sensitivity Level" and "Contact Pads" rows.
 □ Updated Figure 3 and Table 10 on page 9 to reflect specific marking information. Previously, Figure 3 was generic. □ Updated contact information on page 12.
Si533 datasheet revision 1.1 to v1.2 changes:
□ Updated 2.5 V/3.3 V and 1.8 V CML output level specifications for Table 3 on page 3.
□ Added footnotes clarifying max offset frequency test conditions for Table 4 on page 4.
□ Removed the words "Differential Modes: LVPECL/LVDS/CML" in footnote referring to AN256 in Table 4 on page 4.
□ Added CMOS phase jitter specs to Table 4 on page 4.
□ Updated ESD HBM sensitivity rating in Table 7 on page 5.
□ Updated Table 8 on page 5 to include the "Moisture Sensitivity Level" and "Contact Pads" rows.
□ Updated package diagram to include crystal impedance pin in Figure 2 on page 8.
□ Updated Figure 3 and Table 11 on page 9 to reflect specific marking information. Previously, Figure 3 was generic.

Access to online datasheets:

Si530/31 Datasheet v1.2 can be found here:

http://www.silabs.com/Support%20Documents/TechnicalDocs/si530.pdf

Si532 Datasheet v1.2 can be found here:

http://www.silabs.com/Support%20Documents/TechnicalDocs/si532.pdf

Si533 Datasheet v1.2 can be found here:

http://www.silabs.com/Support%20Documents/TechnicalDocs/si533.pdf

Si534 Datasheet v1.2 can be found here:

http://www.silabs.com/Support%20Documents/TechnicalDocs/si534.pdf